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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Salman Akram

Serial No.: 09/388,031 ✓

Filed: September 1, 1999 ✓

For: METALLIZATION STRUCTURES  
FOR SEMICONDUCTOR DEVICE  
INTERCONNECTS, METHODS FOR  
MAKING SAME, AND  
SEMICONDUCTOR DEVICES  
INCLUDING SAME

Examiner: E. Lee

Group Art Unit: 2815

Attorney Docket No.: 3442.2US (96-428)

CERTIFICATE OF MAILING

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AMENDMENT

Box Non Fee Amendment  
Commissioner for Patents  
Washington, D.C. 20231

Sir:

The following amendments and remarks are filed in response to the Examiner's remarks in the Office Action mailed March 1, 2002, the three-month shortened statutory period for response to which expires on June 1, 2002.

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